Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	60	V
Drain-Gate Voltage $R_{GS} \leq 1.0M\Omega$			V_{DGR}	60	V
Gate-Source Voltage		Continuous	V_{GSS}	±20	V
		Pulsed	V_{GSS}	±40	V
Continuous Drain Current (Note 7) V_{GS} = 5V	Steady State	T_A = +25°C T_A = +70°C T_A = +100°C	I_D	0.23 0.18 0.14	A
Maximum Continuous Body Diode Forward Current (Note 7)			I_S	0.53	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I_{DM}	0.8	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	T_A = +25°C	P_D	0.31	W
	T_A = +70°C		0.2	
	T_A = +100°C		0.12	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	410	°C/W
Total Power Dissipation (Note 7)	T_A = +25°C	P_D	0.4	W
	T_A = +70°C		0.25	
	T_A = +100°C		0.15	
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	$R_{\theta JA}$	318	°C/W
Thermal Resistance, Junction to Case (Note 7)	Steady State	$R_{\theta JC}$	135	°C/W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage		BV_{DSS}	60	70	—	V	V_{GS} = 0V, I_D = 10µA
Zero Gate Voltage Drain Current	@ T_C = +25°C @ T_C = +125°C	I_{DSS}	—	—	1.0 500	µA	V_{DS} = 60V, V_{GS} = 0V
Gate-Body Leakage		I_{GSS}	—	—	±10	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage		$V_{GS(TH)}$	1.0	—	2.0	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	@ T_J = +25°C	$R_{DS(ON)}$	—	3.2	7.5	Ω	V_{GS} = 5.0V, I_D = 0.05A
	@ T_J = +125°C			4.4	13.5		V_{GS} = 10V, I_D = 0.5A
On-State Drain Current		$I_{D(ON)}$	0.5	1.0	—	A	V_{GS} = 10V, V_{DS} = 7.5V
Forward Transconductance		g_{FS}	80	—	—	mS	V_{DS} =10V, I_D = 0.2A
Diode Forward Voltage		V_{SD}	—	0.78	1.5	V	V_{GS} = 0V, I_S = 115mA
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance		C_{iss}	—	22	50	pF	V_{DS} = 25V, V_{GS} = 0V f = 1.0MHz
Output Capacitance		C_{oss}	—	11	25	pF	
Reverse Transfer Capacitance		C_{rss}	—	2.0	5.0	pF	
SWITCHING CHARACTERISTICS (Note 9)							
Turn-On Delay Time		$t_{D(ON)}$	—	7.0	20	ns	V_{DD} = 30V, I_D = 0.2A, R_L = 150Ω, V_{GEN} = 10V, R_{GEN} = 25Ω
Turn-Off Delay Time		$t_{D(OFF)}$	—	11.0	20		

Notes: 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
7. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing.

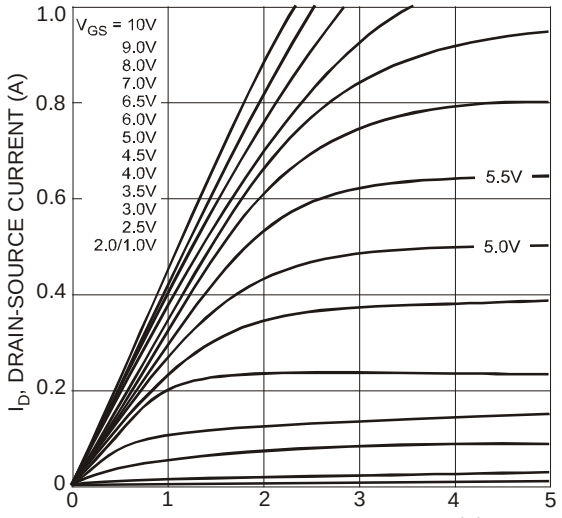

Figure 1 On-Region Characteristics

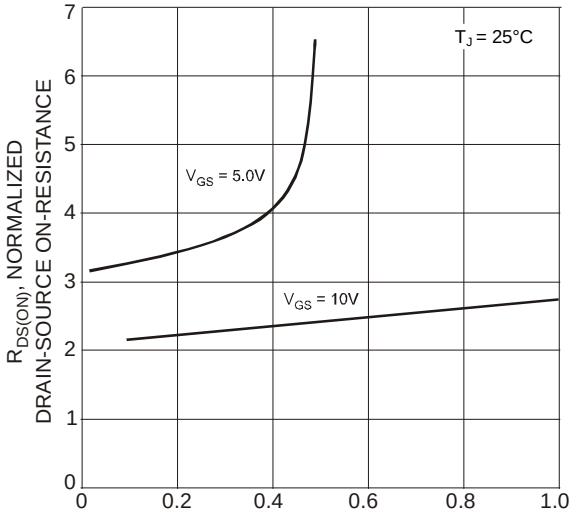

Figure 2 On-Resistance vs. Drain Current

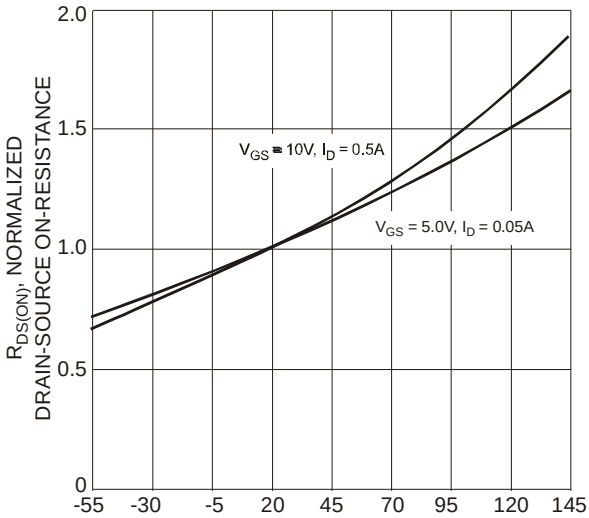

Figure 3 On-Resistance vs. Junction Temperature

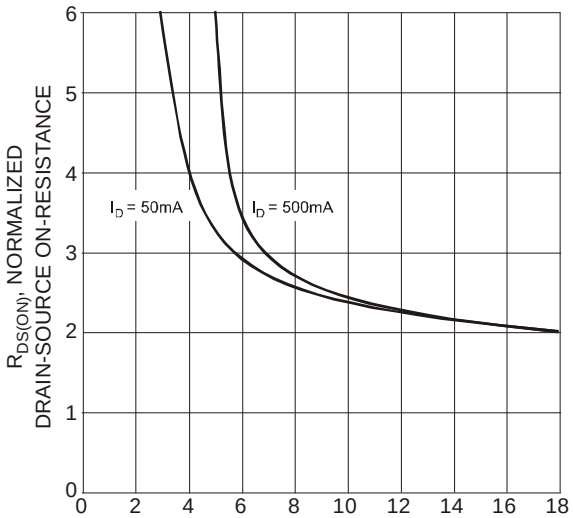

Figure 4 On-Resistance vs. Gate-Source Voltage

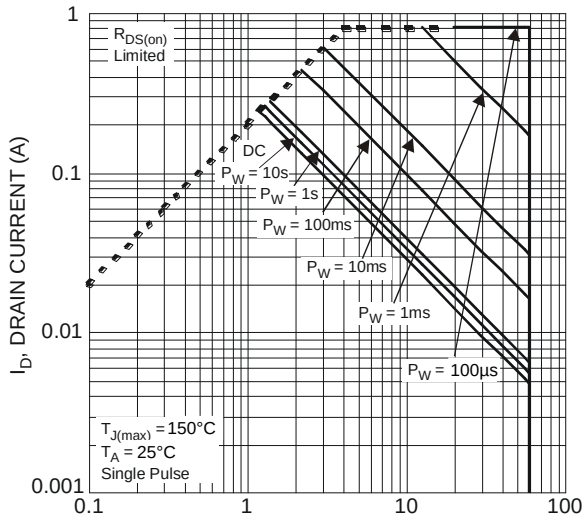

Figure 5 SOA, Safe Operation Area

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

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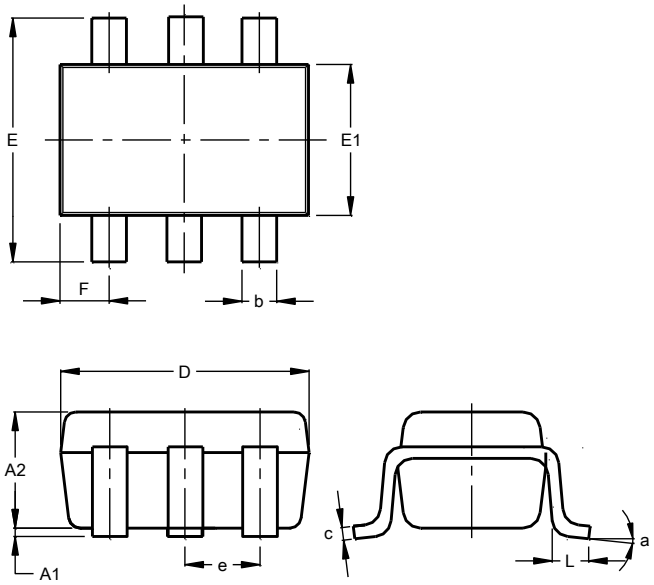

SOT363			
Dim	**Min**	**Max**	**Typ**
A1	0.00	0.10	0.05
A2	0.90	1.00	1.00
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

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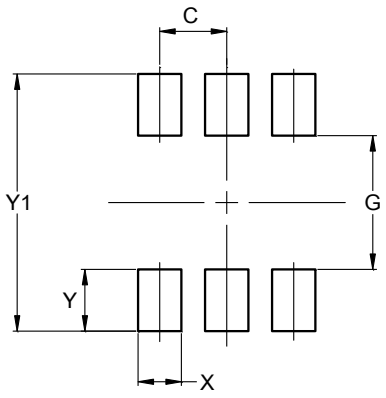

Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

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